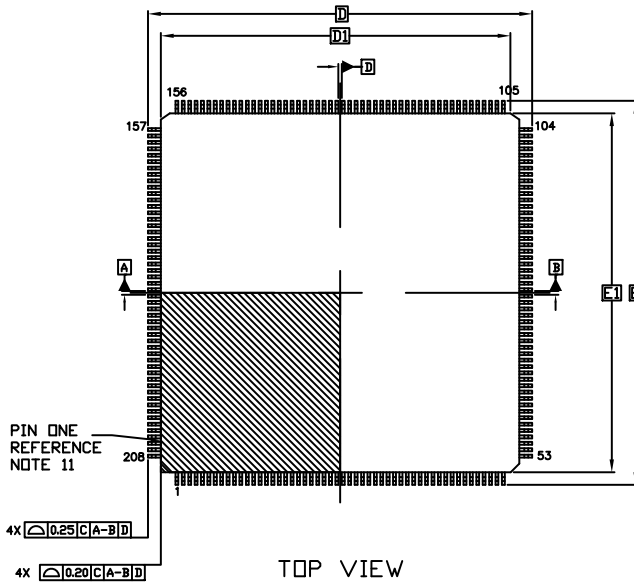




**LQFP 208, 28x28**  
**CASE 561AP**  
**ISSUE A**

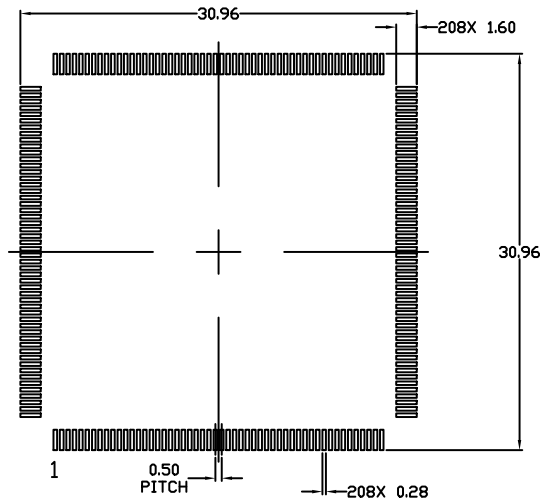
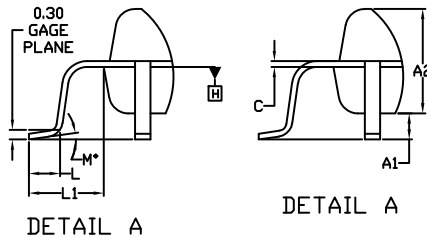
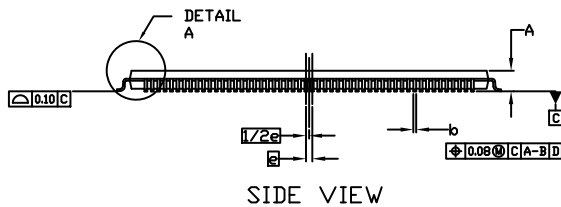
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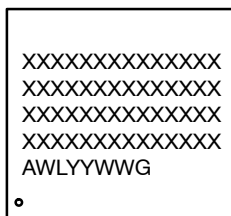
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE IS SMALLER THAN THE BOTTOM PACKAGE SIZE AND TOP PACKAGE WILL NOT OVERHANG THE BOTTOM.
6. DATUM PLANE H IS LOCATED AT THE BOTTOM MOLD PARTING LINE COINCIDENT WITH WHERE THE LEAD EXITS THE BODY.
7. DIMENSIONS D1 AND E1 TO BE DETERMINED AT DATUM PLANE H.
8. DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
9. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
10. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.
11. PIN 1 IS LOCATED IN THIS AREA. MAY APPEAR AS AN EJECTOR MARK, LASER MARK, ETC.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	---	---	1.60
A1	0.05	---	0.15
A2	1.35	1.40	1.45
b	0.17	0.22	0.27
c	0.09	---	0.20
D	30.00 BSC		
D1	28.00 BSC		
E	30.00 BSC		
E1	28.00 BSC		
e	0.50 BSC		
L	0.45	0.60	0.75
L1	1.00 REF		
M	0°	---	7°



**GENERIC MARKING DIAGRAM\***



- A = Assembly Location
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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